



ATTORNEY DOCKET NO.: SS-714-01

U.S. PATENT APPL. NO.: 09/596,837

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Vladimir Vaganov

SERIAL NUMBER: 09/596,837

FILED: June 19, 2000

FOR: Method for Fabricating Microstructures
with Deep Anisotropic Etching of Thick Silicon
Wafers

PATENT

ART UNIT NO.: 1763

EXAMINER: George Z. Goudreau

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DATE OF THIS PAPER:

MAY 13, 2003

I hereby certify that this Response and the documents referred to as enclosed therein are being deposited with the United States Postal Service as First Class Mail on May 13, 2003 addressed to Attn: Mail Stop Non-Fee Amendments, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Debra L. Czapenski

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Attn: Mail Stop Non-Fee Amendments
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Sir:

In response to the Office Action mailed March 17, 2003, please amend the above-identified application as follows: